Request for Proposal

We are a Japanese manufacturer specialized in the production of ultrasonic transducer. We've developed various kinds of transducers as a research and development focused enterprise, just like extremely slim and flexible transducer.
We're not only organizing business development in a non-destructive inspection field, but we have also many offers from medical school or companies in the medical field (for use in breast cancer, knee joints, etc).
We're responding to the customer needs from each field with enhancing the ultrasonic inspection.

We are looking for partners (specifically researchers in ultrasound area) to develop imaging solutions and further innovative products in the medical field.
The partnership includes collaborative research/development, in-licensing/assignment, etc.

Target Field:

• Medical field: "slim and flexible transducer" (e.g. Ultrasonic diagnostic system)
If we enable imaging, we can innovate in breast cancer diagnosis, long-term monitoring, etc.
• Non-destructive inspection field

Evaluation criteria:

• Achievements of Imaging technology in medical field
• Summary of idea to partner with our technologies and products
• What can be done with your collaboration

Proposals should include:

• Overview of the researcher's profile (research abstract, research achievements, academic societies)
• Collaboration experience with companies
• Desired collaboration type (if any)

How to respond to this RFP:

- By submitting a response you represent that the response does not and will not be deemed to contain any confidential information of any kind whatsoever.
- Your response should be an executive summary (free format, within 5 pages, including figures and tables) in English.

Contacts, and deadlines:

• Apply via e-mail to: seobyeong-jang@jp-probe.com (and cc Luca.escoffier@eu-japan.gr.jp)
• For inquiries: Seobyeong Jang, Sales Manager,Japan Probe Co.,LTD (and cc Luca.escoffier@eu-japan.gr.jp)
• Closing date for application: **November 30th, 2019**
• We will provide a feedback to all applicants by the end of December, 2019 by e-mail.